

ABSTRACT OF THE DISCLOSURE

A replaceable light emitting diode (LED) package assembly has a separate structure and manufacturing process of the LED package. The LED die and a set of fluorescent material are located on a substrate. The fluorescent material device can be arranged selectively to match a required emission color according to the characteristic of wavelength of the LED die and not only is blended precisely to provide the required color but also reduces the rate of defects for the individual components of the assembly.